

EMPC 2017 + IMAPS Poland 2017 - CONFERENCE FRAMEWORK PROGRAM

CONFERENCE TOPICS

- I - Advanced packaging and interconnects
- II - Electronics components assembly and PCB solutions
- III - Materials and processes
- IV - Printed, hybrid and flexible electronics
- V - Modeling, design test & reliability
- VI - Functional systems (actuators, sensors, photovoltaics and related)

Sunday, 10 th Sept.			
15:00 – 20:00	REGISTRATION		
18:00 – 20:00	GET-TOGETHER PARTY		
Monday, 11 th Sept.			
08:45 – 10:30	PLENARY SESSION 1 – CONFERENCE OPENING + 2 KEYNOTE LECTURES		
	Session Chairs: Małgorzata Jakubowska (Warsaw University of Technology, Poland) and Martin Schneider-Ramelow (Fraunhofer IZM, Berlin, Germany)		
10:30 – 11:00	Coffee break		
11:00 – 13:00	ORAL SESSION 1 – Advanced Packaging and Interconnects (6 pres.)	ORAL SESSION 2 – Printed, Hybrid and Flexible Electronics (6 pres.)	
	Session Chairs: Andrzej Dziejcz (Wrocław Univ. of Science and Technology) and John Lipp (STFC Rutherford Appleton Laboratory, UK)	Session Chairs: Karlheinz Bock (TU Dresden, Germany) and Agata Skwarek (Inst. of Electron Technology, Cracow Branch, Poland)	
13:00 – 14:00	Lunch		
14:00 – 15:40	ORAL SESSION 3 – Materials and Processes (5 pres.)	ORAL SESSION 4 – Functional Systems (Actuators, Sensors, Photovoltaics and Related) (5 pres.)	
	Session Chairs: Małgorzata Jakubowska (Warsaw Univ. of Technology, Poland) and Uwe Partsch (Fraunhofer IKTS, Dresden, Germany)	Session Chairs: Jerzy Potencki (Rzeszów Univ. of Technology, Poland) and Janusz Sitek (Tele and Radio Research Inst., Warsaw, Poland)	
15:40 – 16:10	Coffee break		
16:10 – 17:30	ORAL SESSION 5 – Materials and Processes (4 pres.)	ORAL SESSION 6 – Modeling, Design Test and Reliability (4 pres.)	
	Session Chairs: Andrzej Dziejcz (Wrocław Univ. of Science and Technology, Poland) and Darko Belavic (Jozef Stefan Inst., Ljubljana, Slovenia)	Session Chairs: Knut E. Aasmundtveit (Univ. College of Southeast Norway) and Krzysztof Górecki (Gdynia Maritime Univ., Poland)	
17:30 – 19:00	POSTER SESSION 1 – Advanced Packaging and Interconnects, Electronics Components Assembly and PCB Solutions, Materials and Processes (13 posters) + IMAPS Poland POSTER SESSION 1 (16 posters)		
	Session Chairs: Nihal Sinnadurai (ATTAC, London, UK) and Ryszard Kisiel (Warsaw Univ. of Technology, Poland)		
19:00 – 21:00	WELCOME RECEPTION		

Tuesday, 12 th Sept.			
09:00 – 10:30	PLENARY SESSION 2 – 2 KEYNOTE LECTURES		
	Session Chairs: Piotr Jasiński (Gdańsk University of Technology, Poland) and Nihal Sinnadurai (ATTAC, London, UK)		
10:30 – 11:00	Coffee break		
11:00 – 13:00	ORAL SESSION 7 – Materials and Processes (6 pres.)	ORAL SESSION 8 – Functional Systems (Actuators, Sensors, Photovoltaics and Related) (6 pres.)	IMAPS Poland ORAL SESSION 1 (6 pres.)
	Session Chairs: Achim Bittner (Hahn-Schickard, Germany) and Yves Ousten (IMS Bordeaux, France)	Session Chairs: Rolf Aschenbrenner (Fraunhofer IZM, Berlin, Germany) and Matti Mantysalo (Tampere Univ. of Technology, Finland)	Session Chairs: Jan Felba (Wrocław Univ. of Science and Technology, Poland) and Piotr Firek (Warsaw Univ. of Technology, Poland)
13:00 – 14:00	Lunch		
14:00 – 15:40	ORAL SESSION 9 – Advanced Packaging and Interconnects (5 pres.)	ORAL SESSION 10 – Modeling, Design Test and Reliability (5 pres.)	IMAPS Poland ORAL SESSION 2 (5 pres.)
	Session Chairs: Johann Nicolics (Vienna Univ. of Technology, Austria) and Klaus Juergen Wolter (TU Dresden, Germany)	Session Chairs: Luigi Calligarich (Electron-Mec Srl., Italy) and Rainer Dudek (Fraunhofer ENAS, Chemnitz, Germany)	Session Chairs: Dariusz Klepacki (Rzeszów Univ. of Technology, Poland) and Piotr Markowski (Wrocław Univ. of Science and Technology, Poland)
15:40 – 16:10	Coffee break		
16:10 – 17:30	ORAL SESSION 11 – Advanced Packaging and Interconnects (4 pres.)	ORAL SESSION 12 – Electronics Components Assembly and PCB Solutions (4 pres.)	
	Session Chairs: Eric Beyne (IMEC Leuven, Belgium) and Martin Schneider-Ramelow (Fraunhofer IZM, Berlin, Germany)	Session Chairs: Alena Pietrikova (Technical Univ. Kosice, Slovakia) and Thomas Zerna (TU Dresden, Germany)	
17:30 – 19:00	POSTER SESSION 2 – Printed, hybrid and flexible electronics, Modeling, Design Test and Reliability, Functional Systems (Actuators, Sensors, Photovoltaics and Related) (13 posters) + IMAPS Poland POSTER SESSION 2 (16 posters)		
	Session Chairs: Paul Collander (Poltronic, Helsinki, Finland) and Leszek Golonka (Wrocław Univ. of Science and Technology, Poland)		
19:00 – 22:30	GALA DINNER		

Wednesday, 13 th Sept.			
09:00 – 9:45	PLENARY SESSION 3 – 1 KEYNOTE LECTURE		
	Session Chair: Jerzy Potencki (Rzeszów University of Technology, Rzeszów, Poland)		
09:45 – 10:15	Coffee break		
10:15 – 12:15	ORAL SESSION 13 – Materials and Processes (6 pres.)	ORAL SESSION 14 – Modeling, Design Test & Reliability (6 pres.)	IMAPS Poland ORAL SESSION 3 (5 pres.)
	Session Chairs: Jens Mueller (TU Ilmenau, Germany) and Marcin Słoma (Warsaw Univ. of Technology, Poland)	Session Chairs: Chris Bailey (University of Greenwich, UK) and Piotr Jasiński (Gdańsk Univ. of Technology)	Session Chairs: Jerzy Potencki (Rzeszów Univ. of Technology, Poland) and Jarosław Kita (Univ. of Bayreuth, Germany)
12:15 – 12:45	CONFERENCE CLOSING + INFORMATION ABOUT ESTC 2018 and EMPC 2019 - Małgorzata Jakubowska (Warsaw University of Technology, Poland), Karlheinz Bock (TU Dresden, Germany) and Luigi Calligarich (Electron-Mec Srl., Italy)		
12:45 – 13:30	Lunch		

13:45 – 15:00

General Assembly Meeting of IMAPS Poland